L Number	Hits	Search Text	DB	Time stamp
1	943	((438/459) or (438/667)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/29 22:28
2	221	(((438/459) or (438/667)).CCLS.) and ((trench or (through adj hole)) near10 (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/29 22:32
3	37	((((438/459) or (438/667)).CCLS.) and ((trench or (through adj hole)) near10 (substrate or wafer))) and ((grind$3 or polish$3) near10 (metal or conduct$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/29 22:32